



PATENT

Case Docket No. MICRON.170A  
Date: October 13, 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Paul A. Farrar  
Appl. No. : 09/909,181  
Filed : July 19, 2001  
For : METHOD OF USING FOAMED  
INSULATORS IN THREE  
DIMENSIONAL MULTICHIP  
STRUCTURES  
Group Art Unit : 2815  
Class/Sub-Class : 257-777000  
Examiner : Chris C. Chu

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

October 15, 2004

(Date)

  
Linda H. Liu, Reg. No. 51,240

TRANSMITTAL LETTER

**MAIL STOP ISSUE FEE**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing is the Issue Fee for the above-identified application:

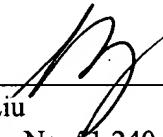
- (X) Form PTOL-85.
- (X) A check in the amount of \$1639 to cover the issue fee, publication fee, and advanced order of copies is enclosed.
- (X) One sheet(s) of drawings.
- (X) The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment, to Account No. 11-1410.

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(X)     Return prepaid postcard.



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